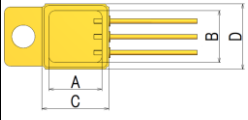
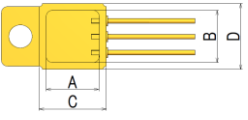
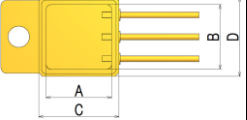
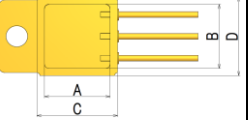
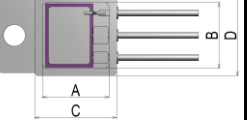
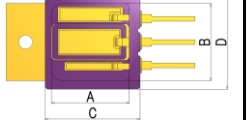
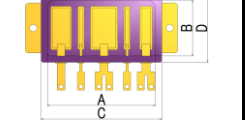


KYOCERA TO CERAMIC PACKAGES (FOR ENGINEERING EVALUATION)

 Inquiries about this list?
Please click here.

R0273A

Unit : mm

No.	1	2	3	4	5	6	7
PACKAGE TYPE	TO-257 PKG	TO-257 PKG	TO-254 PKG	TO-254 PKG	TF-TO254 PKG	TF-TO3P PKG	TF-HB PKG
DRAWING NUMBER	PGMR-A6142	PGMR-A6141	PGMR-A6140	PGMR-A6139	GMR-A9455-A	SGMR-B4385	GMR-B1372
TOP VIEW							
CAVITY A x B	8.35 x 8.35	8.35 x 8.35	11.18 x 11.18	11.18 x 11.18	11.18 x 11.18	18.00 x 18.00	34.20 x 18.00
CERAMIC OVERALL C x D	10.55 x 10.55	10.55 x 10.55	13.72 x 13.72	13.72 x 13.72	13.72 x 13.72	22.00 x 22.00	38.20 x 22.00
TOTAL THICKNESS	5.77	5.27	6.94	6.44	6.49	5.70	6.75
SEAL RING	FeNiCo ALLOY	METALLIZATION	FeNiCo ALLOY	METALLIZATION	METALLIZATION	NO METALLIZATION	NO METALLIZATION
LEAD COUNT	3	3	3	3	3	3	5
LEAD MATERIAL	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	O.F.H.C	O.F.H.C.
HEAT SINK MATERIAL (THERMAL CONDUCTIVITY)	KYCM [®] (260W/mK)	KYCM [®] (260W/mK)	KYCM [®] (260W/mK)	KYCM [®] (260W/mK)	KYCM [®] (260W/mK)	Cu-W (175W/mK)	Cu-W (175W/mK)
MATCHING LID DRAWING NUMBER	PGMR-A9389 (METAL LID)	-	PGMR-A9388 (METAL LID)	SGMR-B3416 (METAL LID)	SGMR-B3416 (METAL LID)	-	-

Note 1. KYCM is a registered trademark of KYOCERA Corporation in Japan.
2. TF-TO254 PKG, TF-TO3P PKG and TF-HB PKG: Courtesy of Osaka University

* Contents in this list are subject to change without notice. It is recommended to confirm the latest information at the time of usage.
We may not be able to accept requests based on old list.